

In the Claims:

1. (Currently Amended) A carrier wherein the carrier comprises:
 - a support structure;
 - first contacts disposed on a first surface of the support structure and arranged in a pattern;
 - elastomer bumps provided on the first surface of the support structure;
 - second contacts formed on the elastomer bumps, wherein the second contacts are electrically connected to the first contacts, ~~wherein the electrical connection of the first contacts to the second contacts is established by conductor tracks rising on the elastomer bumps in a spiral or arcuate manner to a tip of the elastomer bumps; and~~
 - ~~third contacts, arranged in a pattern, disposed on a second surface of the support structure, the second surface opposite to the first surface, wherein the third contacts are electrically connected to the first contacts through conductors in the support structure; and~~
 - at least one opening in the support structure wherein a die placed on the support structure can be is drawn against the elastomer bumps by a force generated by a vacuum and applied through the opening.
2. (Original) The carrier of claim 1 wherein the second contacts are comprised of gold.
3. (Canceled)
4. (Previously Presented) The carrier of claim 1 wherein the conductor tracks comprise a copper-nickel-gold layer construction.

5. (Currently Amended) The carrier of claim [[5]] 1 wherein a gold-gold contact is realized between the die and the carrier by a re-distribution layer arranged on the die.
6. (Currently Amended) The carrier of claim [[1]] 5 wherein the re-distribution layer comprises a copper-nickel-gold layer construction.
7. (Currently Amended) The carrier of claim 1 and further comprising a cover overlying the support structure and capable of being affixed to a frame that is attached to the support structure.
8. (Original) The carrier of claim 7 wherein the cover is formed as a spring element.
9. (Currently Amended) A method of processing a semiconductor die, the method comprising:

providing a semiconductor die, the die including contacts formed in a pattern;

providing a carrier, the carrier comprising of a support structure with first contacts disposed over a surface of a support structure and arranged in a pattern, elastomer bumps provided on the surface of the support structure on which the first contacts are present, and second contacts formed on the elastomer bumps, wherein the second contacts are arranged in a pattern corresponding to the pattern on the die, the second contacts being electrically coupled to the first contacts, wherein the electrical connection of the first contacts to the second contacts is established by conductor tracks rising on the elastomer bumps in a spiral or arcuate manner to a tip of the elastomer bumps, third contacts, arranged in a pattern, disposed on a surface of the support structure opposite to the surface of the support structure on which the first contacts are

present, wherein the third contacts are electrically connected to the first contacts through conductors in the support structure;

placing the die on the support structure of the carrier;
securing the contacts of the die against the elastomer bumps by a predetermined force generated by a vacuum; and

evaluating the semiconductor die by electrically coupling the contact of the die to a tester through the third contacts.

10. (Previously Presented) The method of claim 9 wherein the die is secured by a vacuum until the contacts of the die are fixed against the elastomer bumps.

11. (Original) The method of claim 10 wherein the fixing of the die takes place by a cover, wherein the cover compresses the elastomer bumps with a predetermined pressing force after placing.

12. (Original) The method of claim 11 wherein the pressing force is approximately 2 to 8 grams per elastomer bump.

13. (Original) The method of claim 11 wherein the cover is formed as a spring element.

14. (Original) The method of claim 9 wherein providing a semiconductor die comprises:
fabricating a wafer that includes a plurality of semiconductor dies; and
separating the wafer to provide the semiconductor die.

15. (Original) The method of claim 9 wherein evaluating the semiconductor die comprises testing the semiconductor die.

16. (Original) The method of claim 9 wherein evaluating the semiconductor die comprises burning-in the semiconductor die.

17. (Original) The method of claim 9 wherein the second contacts of the carrier are comprised of gold.

18. (Canceled)

19. (Previously Presented) The carrier of claim 9 wherein the conductor tracks comprise a copper-nickel-gold layer construction.

20. (Original) The carrier of claim 9 wherein a gold-gold contact is realized between the die and the carrier by re-distribution layers being arranged on the die, and wherein the re-distribution layers comprise a copper-nickel-gold layer construction.

21. (Currently Amended) A carrier comprising:

a support structure;

a frame fastened on the support structure on a first surface and including four walls to surround [[a]] the first surface of the support structure of a size that corresponds to a size of a semiconductor die, an upper portion of the walls being beveled in a direction toward the first

surface;

first contacts disposed on the first surface of the support structure;
elastomer bumps disposed on the first surface of the support structure;
second contacts formed on the elastomer bumps, wherein the second contacts are
electrically connected to the first contacts; and
third contacts, arranged in a pattern, disposed on a second surface of the support
structure, the second surface opposite to the first surface, wherein the third contacts are
electrically connected to the first contacts through conductors in the support structure; and
at least one opening in the support structure wherein a the die placed on the support
structure can be is drawn against the elastomer bumps by a force generated by a vacuum and
applied through the opening.

22. (Previously Presented) The carrier of claim 21 and further comprising a cover overlying
the support structure, wherein the cover is formed as a spring element.

23. (New) The second contacts of Claim 1 wherein the electrical connection of the first
contacts to the second contacts is established by conductor tracks rising on the elastomer bumps
in a spiral or arcuate manner to a tip of the elastomer bumps.

24. (New) The second contacts of Claim 9 wherein the electrical connection of the first
contacts to the second contacts is established by conductor tracks rising on the elastomer bumps
in a spiral or arcuate manner to a tip of the elastomer bumps.